IN THE CLAIMS:

Claims 2 and 4 through 12 were previously withdrawn from consideration and are cancelled herein. Claims 1 and 3 have been amended herein. All of the pending claims are presented below. Please enter these claims as amended.

- 1. (Currently amended) An electronic device assembly for a substrate having circuits thereon comprising:
- an integrated circuit semiconductor die having at least one bond pad thereon for attachment in one of a conventional die attach to lead frame connect process and a LOC connect process;
- a conductive plastic lead frame having a plurality of lead fingers, said the conductive plastic lead frame including a plastic lead frame structure having a conductive polymeric material located on at least a portion of said the plurality of lead fingers and formed by one of compression molding and injection molding, a portion of each of the plurality of lead fingers formed for contacting a circuit of said the circuits of said the substrate;
- an adhesive attaching a portion of-said-the integrated circuit semiconductor die to a portion of said-the conductive plastic lead frame;
- at least one connector connecting said the at least one bond pad of said the integrated circuit semiconductor die to at least one lead finger of said the plurality of lead fingers of the conductive plastic lead frame; and
- encapsulating material for encapsulating at least a portion of said the integrated circuit semiconductor die and for encapsulating at least a portion of the at least one lead finger of said the conductive plastic lead frame.
 - 2. (Currently cancelled)

- 3. (Currently amended) An electronic device assembly for a substrate having a plurality of circuits thereon comprising:
- an integrated circuit semiconductor die having at least one bond pad thereon for attachment in one of a conventional die attach to lead frame connect process and a LOC connect process;
- a conductive plastic lead frame having a plurality of lead fingers, said the conductive plastic lead frame including a plastic lead frame structure having a conductive polymeric material located on at least a portion of said the plurality of lead fingers, a portion of each of the plurality of lead fingers formed for contacting a circuit of said the circuits of said the substrate;
- an adhesive for attaching a portion of <u>said</u> the integrated circuit semiconductor die to a portion of <u>said</u> the conductive plastic lead frame;
- at least one connector connecting <u>said</u> the at least one bond pad of <u>said</u> the integrated circuit semiconductor die to at least one lead finger of <u>said</u> the conductive plastic lead frame; and
- encapsulating material for encapsulating at least a portion of said the integrated circuit semiconductor die and for encapsulating at least a portion of said the at least one lead finger of said the conductive plastic lead frame.
 - 4.-12. (Currently cancelled)